



WHM200A

P/N : WSWHM200A00

DATA SHEET / REV0.32

SJIT Co.,Ltd

54-11, Dongtanhana 1-gil, Hwaseong-si, Gyeonggi-do, South Korea

<http://sjit.company>

Document Information

File name	DS_WHM200A_HaLow_US_High_Power_R031_240812.pdf
Created	2024-08-12
Total pages	25page

Revision History

Rev.	Date	Note	Remark
0.0	23.07.14	Preliminary	
0.1	23.12.23	1) Change Company name SJI → SJIT	1 page
0.2	24.01.19	1) Change Packing Quantity - Reel : 500EA → 480EA - Box : 2,500EA → 2400EA	21 page
0.3	24.02.08	1) FCC certification completed	19 page
0.31	24.02.15	- Update Transmitter(Max Power by Country Code)	8 page
0.32	24.08.12	- Change the wrong part(3.1 Absolute Maximum Ratings) VDD_FEM : -0.5 ~ 3.8V → -1.0 ~ 6.0V	6 page

Aim of this Document

The aim of this document is to give a detailed product description including interfaces, features and performance of the module WHM200A.

Table of Contents

1. Introduction	4
1.1 Key Features	4
1.2 Applications	4
2. Description	5
2.1 CPU	5
2.2 Memory	5
3. Electrical Characteristics	6
3.1 Absolute Maximum Ratings.....	6
3.2 Recommended Operating Condition	6
3.3 Electrical Specification	7
3.4 RF Characteristics	8
3.4.1 Transmitter(Max Power by Country Code)	8
3.4.2 Transmitter(TBD)	9
3.4.3 Receive Sensitivity	10
3.4.4 Output Power vs. Input Voltage(VDD) table	11
4. Module Package	12
4.1 Pinout Description	12
4.2 Module Dimensions.....	14
4.3 Recommended Footprint.....	14
4.4 Recommended PCB design guide	15
4.5 Reflow Profile of Module	16
5. Integration Guide	17
5.1 Mode Pin Setting	17
5.2 Typical Application Schematic.....	18
6. Laser Marking	19
7. Packing	21
7.1 Reel Packing.....	21
7.2 Packing Box.....	22
7.2 Packing Bag & Silica Gel	23
8. Notice	24

1. Introduction

The WHM200A uses the new Wi-Fi standard IEEE 802.11ah, which uses the Sub 1 GHz license-exempt band. It has long range, low power and high permeability and is optimized for IoT modules.

The WHM200A includes a RF switch and an internal PA in the SoC to increase transmit power up to 23 ± 2 dBm.

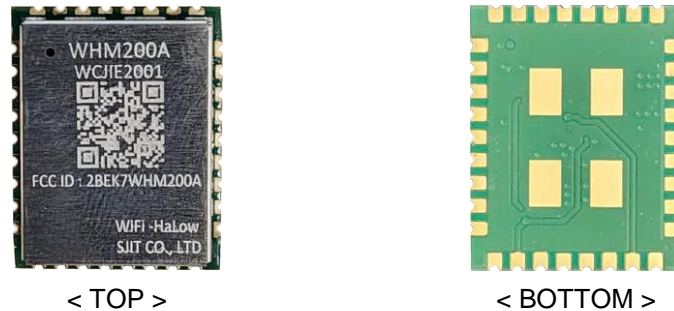


Figure 1-1: Picture of WHM200A

1.1 Key Features

- Compact module 14 x 17.5 x 2.8mm. (Typ.)
- Full IEEE 802.11ah compatibility with enhanced performance
- AP and STA, mesh network support
- UART and SPI support for host interface
- Low-Power Long Range Transceiver operating in the sub-1GHz ISM band
- RF interface optimized to 50 Ω .
- Output Power Level up to 23 ± 2 dBm(FCC Certified)
- -107 dBm minimum receive sensitivity (MCS10)

1.2 Applications

- Smart home and home security
- Smart factory and factory automation
- Smart city and public transportation management
- Smart grid/metering
- Surveillance camera and remote monitoring of wildlife
- Wireless sensor network
- Health care
- Electric vehicle and charging
- Commercial drone
- Wireless Alarm and Security Systems.

2. Description

The WHM200A is a long range, high-performance module for wireless communication. The module is solder-able like a SMD component and can easily be mounted on a simple carrier board with a minimum of required external connections.

It includes all necessary passive components for wireless communication as depicted in the following figure.

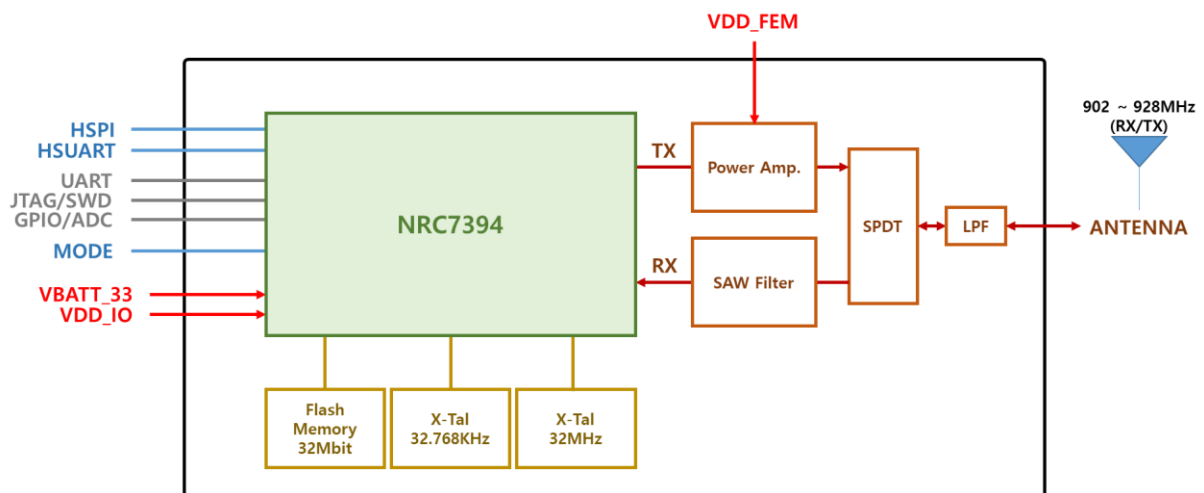


Figure 2-1: Block Diagram

2.1 CPU

- ARM® Cortex-M3 for IEEE 802.11ah WLAN and application
- Clock frequencies for processor(Max 32MHz)

2.2 Memory

- CPU Internal Memory
 - ▲ 32KB Boot ROM
 - ▲ 1,088KB system SRAM
 - ▲ 192KB Key Memory for security
 - ▲ 16KB cache for XIP
- CPU External Memory
 - ▲ 32Mbit Flash Memory

3. Electrical Characteristics

In the following different electrical characteristics of the WHM200A are listed.

- Note: Stress exceeding of one or more of the limiting values listed under “Absolute Maximum Ratings” may cause permanent damage to the radio module

3.1 Absolute Maximum Ratings

Parameter		Min	Max	Unit
Storage Temperature		-40	+125	°C
Supply Voltage	VBATT	-0.5	3.8	V
	VDD_IO	-0.5	3.8	V
	VDD_FEM	-1.0	6.0	V

Table 3-1-1: Absolute Maximum Ratings

3.2 Recommended Operating Condition

Parameter		Min	Typ	Max	Unit
Operating temperature range		-40	-	+85	°C
Operating Voltage	VBATT	2.4	3.3	3.6	V
	VDD_IO	1.68	3.3	3.6	V
	VDD_FEM	3.0	3.3	4.5	V
Operating current (peak) Tx @1M/MCS10/27dBm	VBATT	170			mA
	VDD_IO	2			mA
	VDD_FEM	800			mA
Operation Clock Frequency	Transceiver		32		MHz
	MCU RTC		32.768		kHz

Table 3-2-1: Operating Condition

3.3 Electrical Specification

MODE	DUT Status	VDD_IO (mA)	VBATT (mA)	VDD_FEM (mA)
802.11ah	Tx @ 0 dBm	1.0	94	110
	Tx @ 10 dBm	1.0	99	141
	Tx @ 15 dBm	1.0	101	182
	Tx @ 20 dBm	1.0	120	300
	Tx @ 25 dBm	1.0	142	471
	Continuous Rx @ -85 dBm	2	25	-

Notes :

Unless otherwise specified, TA.=25°C, VBATT= 3.3V, Continuous Mode, 1M, MCS0, 915.5MHz

Table 3-3-1: Current Consumption

3.4 RF Characteristics

3.4.1 Transmitter(Max Power by Country Code)

Country Code	BandWidth	CF	Max Power	USE
US	1 MHz	902.5 MHz	-	Not Use
	1 MHz	903.5 MHz	23dBm ± 2dB	USE
	1 MHz	904.5 MHz	23dBm ± 2dB	USE
	1 MHz	905.5 MHz	23dBm ± 2dB	USE
	1 MHz	906.5 MHz	23dBm ± 2dB	USE
	1 MHz	907.5 MHz	23dBm ± 2dB	USE
	1 MHz	908.5 MHz	23dBm ± 2dB	USE
	1 MHz	909.5 MHz	23dBm ± 2dB	USE
	1 MHz	910.5 MHz	23dBm ± 2dB	USE
	1 MHz	911.5 MHz	23dBm ± 2dB	USE
	1 MHz	912.5 MHz	23dBm ± 2dB	USE
	1 MHz	913.5 MHz	23dBm ± 2dB	USE
	1 MHz	914.5 MHz	23dBm ± 2dB	USE
	1 MHz	915.5 MHz	23dBm ± 2dB	USE
	1 MHz	916.5 MHz	23dBm ± 2dB	USE
	1 MHz	917.5 MHz	23dBm ± 2dB	USE
	1 MHz	918.5 MHz	23dBm ± 2dB	USE
	1 MHz	919.5 MHz	23dBm ± 2dB	USE
	1 MHz	920.5 MHz	23dBm ± 2dB	USE
	1 MHz	921.5 MHz	23dBm ± 2dB	USE
	1 MHz	922.5 MHz	23dBm ± 2dB	USE
	1 MHz	923.5 MHz	23dBm ± 2dB	USE
	1 MHz	924.5 MHz	23dBm ± 2dB	USE
	1 MHz	925.5 MHz	23dBm ± 2dB	USE
	1 MHz	926.5 MHz	23dBm ± 2dB	USE
	1 MHz	927.5 MHz	-	Not Use
	2 MHz	903.0 MHz	-	Not Use
	2 MHz	905.0 MHz	23dBm ± 2dB	USE
	2 MHz	907.0 MHz	23dBm ± 2dB	USE
	2 MHz	909.0 MHz	23dBm ± 2dB	USE
	2 MHz	911.0 MHz	23dBm ± 2dB	USE
	2 MHz	913.0 MHz	23dBm ± 2dB	USE
	2 MHz	915.0 MHz	23dBm ± 2dB	USE
	2 MHz	917.0 MHz	23dBm ± 2dB	USE
	2 MHz	919.0 MHz	23dBm ± 2dB	USE
	2 MHz	921.0 MHz	23dBm ± 2dB	USE
	2 MHz	923.0 MHz	23dBm ± 2dB	USE
	2 MHz	925.0 MHz	23dBm ± 2dB	USE
	2 MHz	927.0 MHz	-	Not Use
	4 MHz	906.0 MHz	21dBm ± 2dB	USE
	4 MHz	910.0 MHz	23dBm ± 2dB	USE
	4 MHz	914.0 MHz	23dBm ± 2dB	USE
	4 MHz	918.0 MHz	23dBm ± 2dB	USE
	4 MHz	922.0 MHz	23dBm ± 2dB	USE
4 MHz	926.0 MHz	-	Not Use	

Table 3-4-1-1: Technical Regulations.

3.4.2 Transmitter

Band	BW	MCS	Modulation/ Coding Rate	EVM spec [dB]	Max. Power [dBm]	
					VDD_FEM 3.3V	VDD_FEM 4.5V
902 ~ 928 MHz	1 MHz	10	BPSK 1/2 rep. 2x	-4	28	28
		0	BPSK 1/2	-5	28	28
		1	QPSK 1/2	-10	28	28
		2	QPSK 3/4	-13	28	28
		3	16QAM 1/2	-16	27	27
		4	16QAM 3/4	-19	27	27
		5	64QAM 2/3	-22	26	26
		6	64QAM 3/4	-25	24	25
		7	64QAM 5/6	-27	22	23
	2 MHz	0	BPSK 1/2	-5	28	28
		1	QPSK 1/2	-10	28	28
		2	QPSK 3/4	-13	28	28
		3	16QAM 1/2	-16	27	27
		4	16QAM 3/4	-19	26	27
		5	64QAM 2/3	-22	25	26
		6	64QAM 3/4	-25	24	25
		7	64QAM 5/6	-27	24	24
	4 MHz	0	BPSK 1/2	-5	29	29
		1	QPSK 1/2	-10	29	29
		2	QPSK 3/4	-13	28	29
		3	16QAM 1/2	-16	27	28
		4	16QAM 3/4	-19	27	27
		5	64QAM 2/3	-22	26	26
		6	64QAM 3/4	-25	25	26
		7	64QAM 5/6	-27	25	26

※ T = 25°C, if nothing else stated

Table 3-4-2-1: Transmitter(Module's Max Power)

3.4.3 Receive Sensitivity

BW	MCS	Modulation / Coding Rate	11ah spec	Min. Sensitivity [dBm]		
				Min	Typ	Max
1 MHz	10	BPSK ½ rep. 2x	-98		-106	
	0	BPSK ½	-95		-103	
	1	QPSK ½	-92		-102	
	2	QPSK ¾	-90		-100	
	3	16QAM ½	-87		-97	
	4	16QAM ¾	-83		-94	
	5	64QAM ⅔	-79		-89	
	6	64QAM ¾	-78		-88	
	7	64QAM 5/6	-77		-87	
2 MHz	0	BPSK ½	-92		-100	
	1	QPSK ½	-89		-98	
	2	QPSK ¾	-87		-96	
	3	16QAM ½	-84		-93	
	4	16QAM ¾	-80		-90	
	5	64QAM ⅔	-76		-86	
	6	64QAM ¾	-75		-83	
	7	64QAM 5/6	-74		-82	
4 MHz	0	BPSK 1/2	-89		-98	
	1	QPSK 1/2	-86		-95	
	2	QPSK 3/4	-84		-93	
	3	16QAM 1/2	-81		-90	
	4	16QAM 3/4	-77		-87	
	5	64QAM 2/3	-73		-83	
	6	64QAM 3/4	-72		-81	
	7	64QAM 5/6	-71		-80	

Figure 3-4-3-1: Receive Sensitivity

3.4.4 Output Power vs. Input Voltage(VDD) table

Input Voltage(VDD)	2.4V	2.6V	2.8V	3.0V	3.2V	3.3V	3.6V	3.8V	4.0V	4.2V	4.5V
Output Power (Typ.) / dBm	15.55	19.9	21.4	21.99	22.06	22.15	22.1	22.11	22.04	22.1	22.04
※ T = 25°C, MCS7, VDD_IO=3.3V, 1M Bandwidth, Target Power : 22dB											

Table 3-4-4-1: Output Power vs. Input Voltage

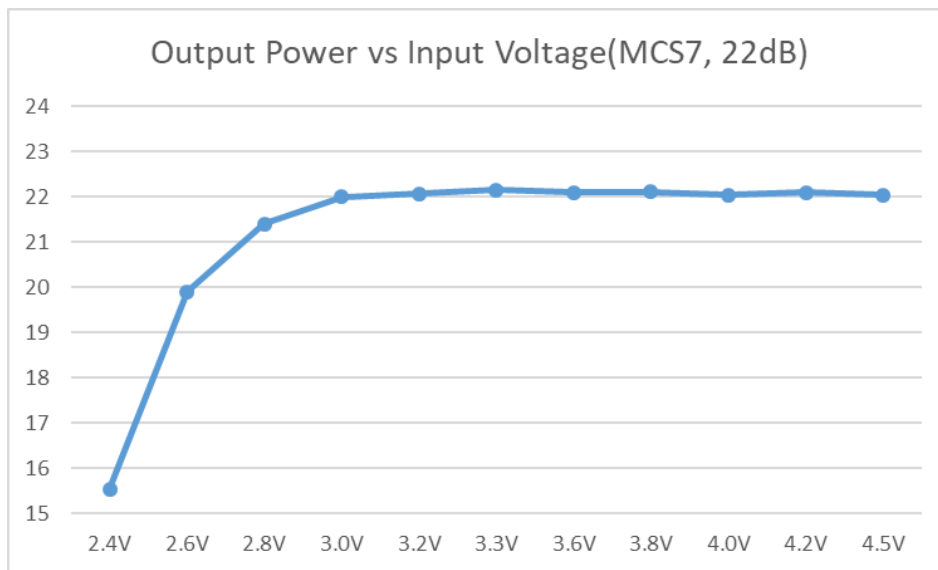


Figure 3-4-4-1: Output Power vs. Input Voltage Graph

4. Module Package

In the following the WHM200A module package is described. This description includes the WHM200A pinout as well as the modules dimensions. Furthermore a recommendation for a suitable footprint is given, which should be used for further mounting on appropriate carrier boards.

4.1 Pinout Description

Figure 4-1-1 depicts a description of the WHM200A's pads on the bottom side. The figure shows the module with its pinout in top view (right figure). A detailed description of the individual pins can be found in Table 4-1-1: Pinout Table.

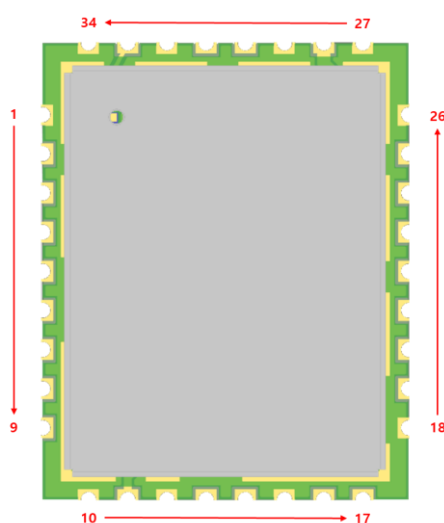


Figure 4-1-1: Description of module pins and top view

Pin No	Name	Direction	Description	GPIO Function
1	GND	GND		
2	UART1_TXD/GP12	O	UART channel1 Tx data	GP12
3	UART1_RXD/GP13	I	UART channel1 Rx data	GP13
4	UART1_CTS/GP14	I	UART channel1 clear to send	GP14
5	UART1_RTS/GP20	O	UART channel1 request to send	GP20
6	Mode/GP19	I	Boot mode (0: ROM boot, 1: XIP boot)	GP19
7	ADC0/GP17	I	Auxiliary ADC channel 0	GP17
8	ADC1/GP18	I	Auxiliary ADC channel 1	GP18
9	GP25	I/O	GPIO	GP25
10	GND	GND		
11	VDD_IO	P	NRC7394 I/O power input	

12	GND	GND		
13	UART0_RXD/GP09	I	UART channel0 Rx data	GP09
14	UART0_TXD/GP08	O	UART channel0 Tx data	GP08
15	GND	GND		
16	VBATT	P	NRC7394 PMS, RF/PA power input	
17	PMS_nPOR/nRST	I/O	NRC7394 reset (active low) input, POR reset output (internal pull-up)	
18	GND	GND		
19	HSPI_nCS/GP28	I	Host SPI – chip select (active low)	GP28
20	HSPI_MISO/GP29	O	Host SPI – master in slave out	GP29
21	HSPI_MOSI/GP06	I	Host SPI – master out slave in	GP06
22	HSPI_CLK/GP07	I	Host SPI – clock	GP07
23	HSPI_nEIRQ/GP30	O	Host SPI – interrupt (active low)	GP30
24	SWD_IO/GP10	I/O	SWD data	GP10
25	SWD_CLK/GP11	I	SWD clock	GP11
26	GND	GND		
27	GND	GND		
28	VDD_FEM	P	Power AMP Power input	
29	GND	GND		
30	NC			
31	NC			
32	GND	GND		
33	RF_ANT	I/O	RF input/output	
34	GND	GND		

Table 4-1-1: Pinout Table

4.2 Module Dimensions

The outer dimensions of the WHM200A are given by Figure 4-2-1.

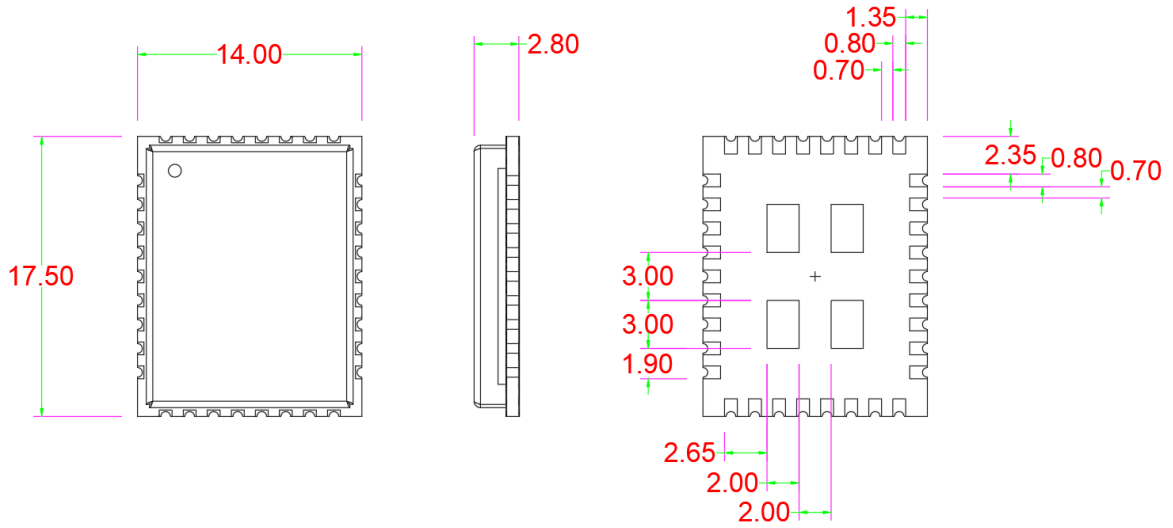


Figure 4-2-1: Outer Dimensions

4.3 Recommended Footprint

According to Chapter 4.2, a recommendation for the footprint of the WHM200A is given by Figure 4-3-1.

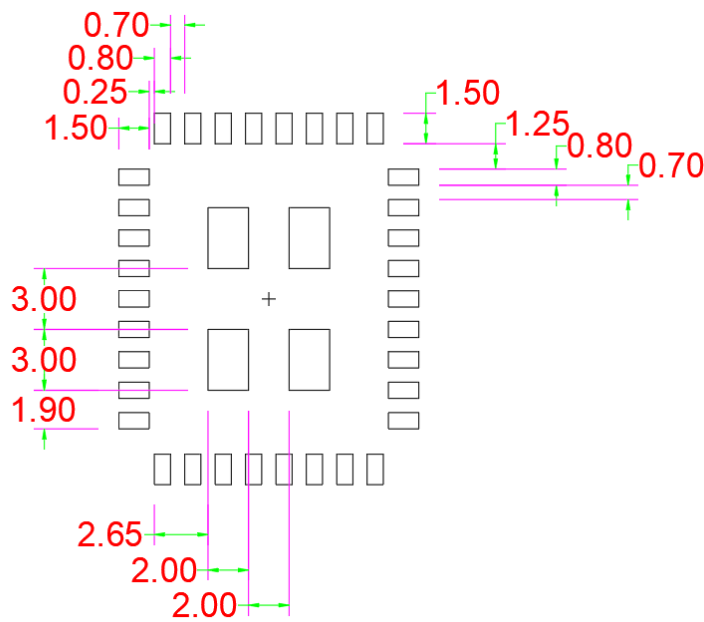


Figure 4-3-1: Recommended footprint (top view)

4.4 Recommended PCB design guide

To protect a contact short or electrical shock when WHM200A module is mounted on customer's board, we recommend PSR ink-coating(Green Area) of top side at module mount area on customer's board as Figure 4-4-1.

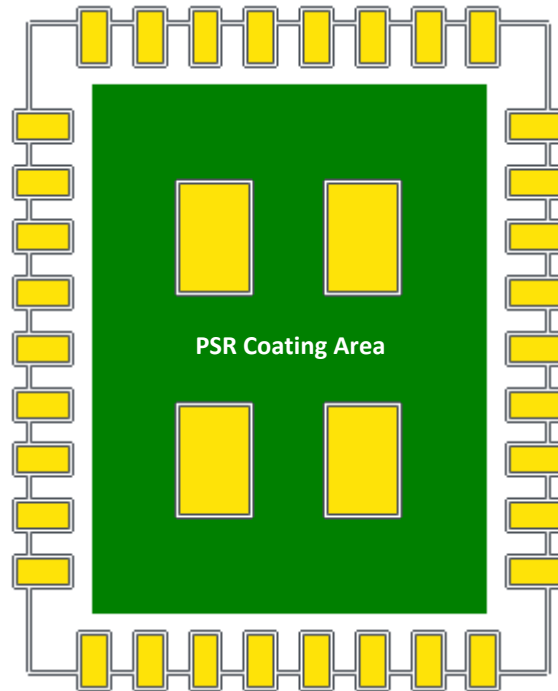


Figure 4-4-1: PSR ink Coating of mount board

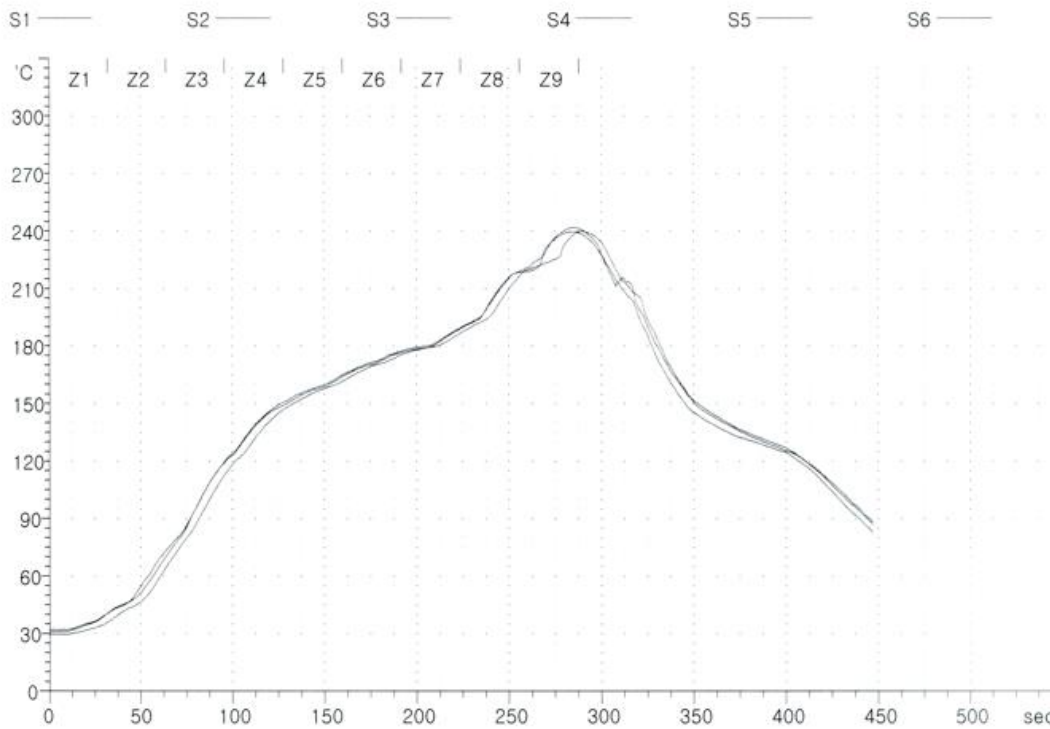
4.5 Reflow Profile of Module

Zone Setting Temperature									
	Z1	Z2	Z3	Z4	Z5	Z6	Z7	Z8	Z9
Upper	150	160	170	180	190	200	220	250	285
Lower	150	160	170	180	190	200	220	250	285
Length	400	400	400	400	400	400	400	400	400

Machine No :
Line Speed : 0.75 m/min
Line Length : 3600 mm

Temperature Analysis & Temperature Zone														
	Max °C	at-sec	ov-220	T1-s	T2-s	T3-s	T4-s	T5-s	T1-°C/s	T2-°C/s	T3-°C/s	T4-°C/s	T5-°C/s	
S1	241.7	285.5	45.5	56.0	83.5	66.5	45.5	0.0	+1.1	+0.7	+0.5	+0.2	+0.0	
S2	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	+0.0	+0.0	+0.0	+0.0	+0.0	
S3	239.6	283.0	40.5	56.5	84.5	65.0	40.5	0.0	+1.1	+0.7	+0.5	+0.2	+0.0	
S4	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	+0.0	+0.0	+0.0	+0.0	+0.0	
S5	0.0	0.0	0.0	0.0	0.0	0.0	0.0	0.0	+0.0	+0.0	+0.0	+0.0	+0.0	
S6	239.9	290.0	47.0	54.5	84.5	65.0	47.0	0.0	+1.2	+0.7	+0.5	+0.2	+0.0	

T1: 50 ~ 100 °C T2: 100 ~ 170 °C T3: 170 ~ 200 °C T4: 220 ~ °C T5: 0 ~ 0 °C



SEILIECO

SMP-306

Printed at 2022-02-22 19:34:09

SPEC	Pre-heat	Soak	Ramp	PEAK
	50~100°C	100~170°C	220°C 이상	240°C
	1~2°C/sec	60~100 sec	30~50 sec	±5°C
Result	1.13	84	44.3	239.4
	OK	OK	OK	OK

5. Integration Guide

The WHM200A provides 34 connectors as described in Chapter 5. For integrating the WHM200A into an environment, a typically circuit as given in Chapter 5.1 can be used.

5.1 Mode Pin Setting

MODE pin is provided for boot mode selection to offer flexible and configurable boot options as shown in Table below

In the case of XIP boot, it is necessary to change to XIP boot mode after FW upload, so users need to install a switch that can control the mode pins on the board

MODE pin	Description
VDD	<p>XIP boot mode</p> <p>Firmware must be downloaded to external flash memory before power on. The start address for boot is remapped to the start address of flash memory.</p>
GND	<p>ROM boot mode</p> <p>Boot from internal ROM code and wait for external command via HSPI or UART. The start address for boot is remapped to the start address of ROM memory.</p>
	<p>FW upload mode</p> <p>Firmware upgrade to external flash memory or upload to internal SRAM via UART0.</p>

5.2 Typical Application Schematic

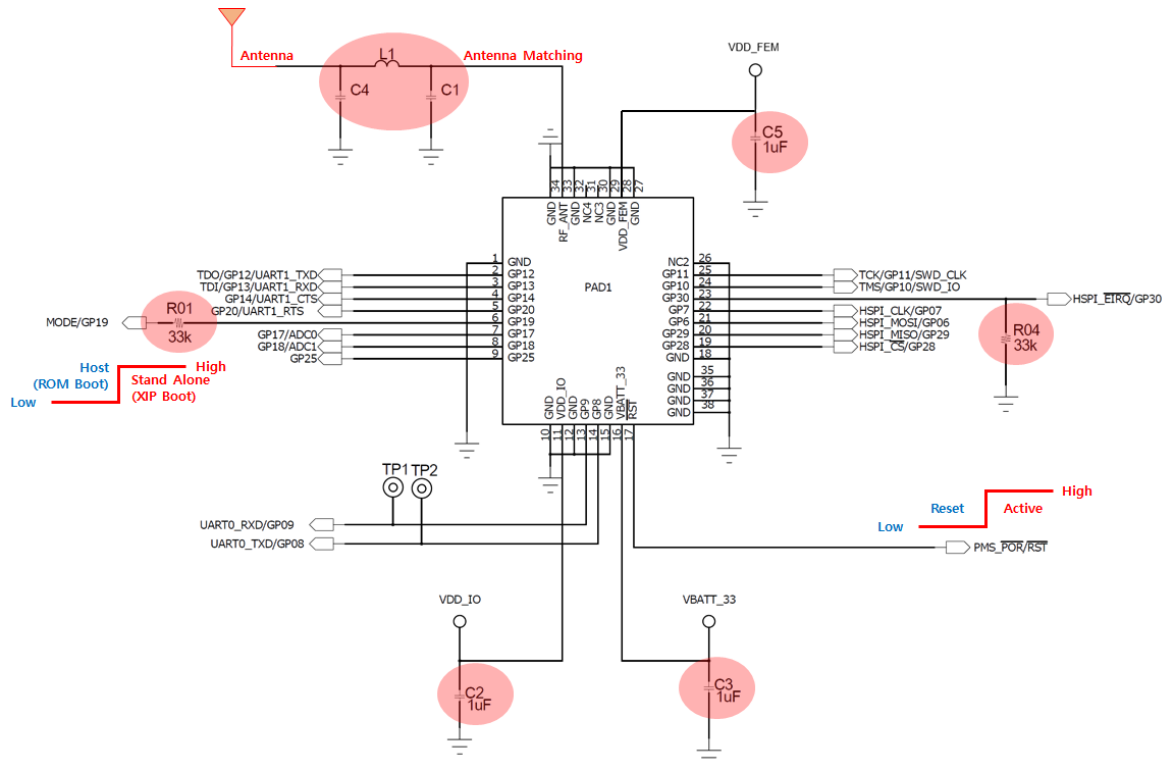


Figure 5-2-1: Typical Application Schematic

6. Laser Marking



FCC ID	2BEK7WHM200A
--------	--------------

“This Module may cause radio interference while in use and may cause harmful interference from other devices”

WHM200A Lot, No(9digits) Information

W	A	K	A	V	2	0	0	1
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

No.	EXPLANATION																
②	Blue Tooth(B), Wi-Fi(W) , Zigbee(Z), Combo(C) , NFC(N)																
②	Manufacture Area <table border="1"> <thead> <tr> <th>Packing Lot</th> <th>A</th> <th>B</th> <th>C</th> </tr> </thead> <tbody> <tr> <td>Area</td> <td>Korea</td> <td>China</td> <td>Vietnam</td> </tr> </tbody> </table>	Packing Lot	A	B	C	Area	Korea	China	Vietnam								
Packing Lot	A	B	C														
Area	Korea	China	Vietnam														
③	Year <table border="1"> <thead> <tr> <th>Year</th> <th>2021</th> <th>2022</th> <th>2023</th> <th>2024</th> <th>2025</th> <th>2026</th> <th>2027</th> </tr> </thead> <tbody> <tr> <td>Mark</td> <td>H</td> <td>I</td> <td>J</td> <td>K</td> <td>L</td> <td>M</td> <td>N</td> </tr> </tbody> </table>	Year	2021	2022	2023	2024	2025	2026	2027	Mark	H	I	J	K	L	M	N
Year	2021	2022	2023	2024	2025	2026	2027										
Mark	H	I	J	K	L	M	N										

④	Month												
	Month	1	2	3	4	5	6	7	8	9	10	11	12
	Mark	A	B	C	D	E	F	G	H	I	J	K	L
⑤	Day												
	Day	1	2	3	4	5	6	7	8	9	10		
	Mark	1	2	3	4	5	6	7	8	9	A		
	Day	11	12	13	14	15	16	17	18	19	20		
	Mark	B	C	D	E	F	G	H	I	J	K		
	Day	21	22	23	24	25	26	27	28	29	30	31	
Mark	L	M	N	O	P	Q	R	S	T	U	V		
⑥⑦	Model Serial Number (WHM200A : US High Power)												
⑧⑨	A Serial Number(1serial: 1Box)												

WHM200A QR-code(44digits) Information



← ex) 200AXK1ER01000001G,88571DF1AD1D,88571DF1AD1F

Digits	QR code info	Description
1~18	Serial(Lot) No.	200AXK1ER01000001G
19	,	Comma
20~31	WIFI MAC0	Mac Address 12digits
32	,	Comma
33~44	WIFI MAC1	Mac Address 12digits

Serial No.

Model	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
	MODEL CODE				ASSY	YEAR	Month	Day	HW version			SW App.	SW Ver.	SERIAL NUMBER			Customer	
WHM200A	2	0	0	A	X	K	1	E	R	0	1	0	0	0	0	0	1	G

7. Packing

7.1 Reel Packing

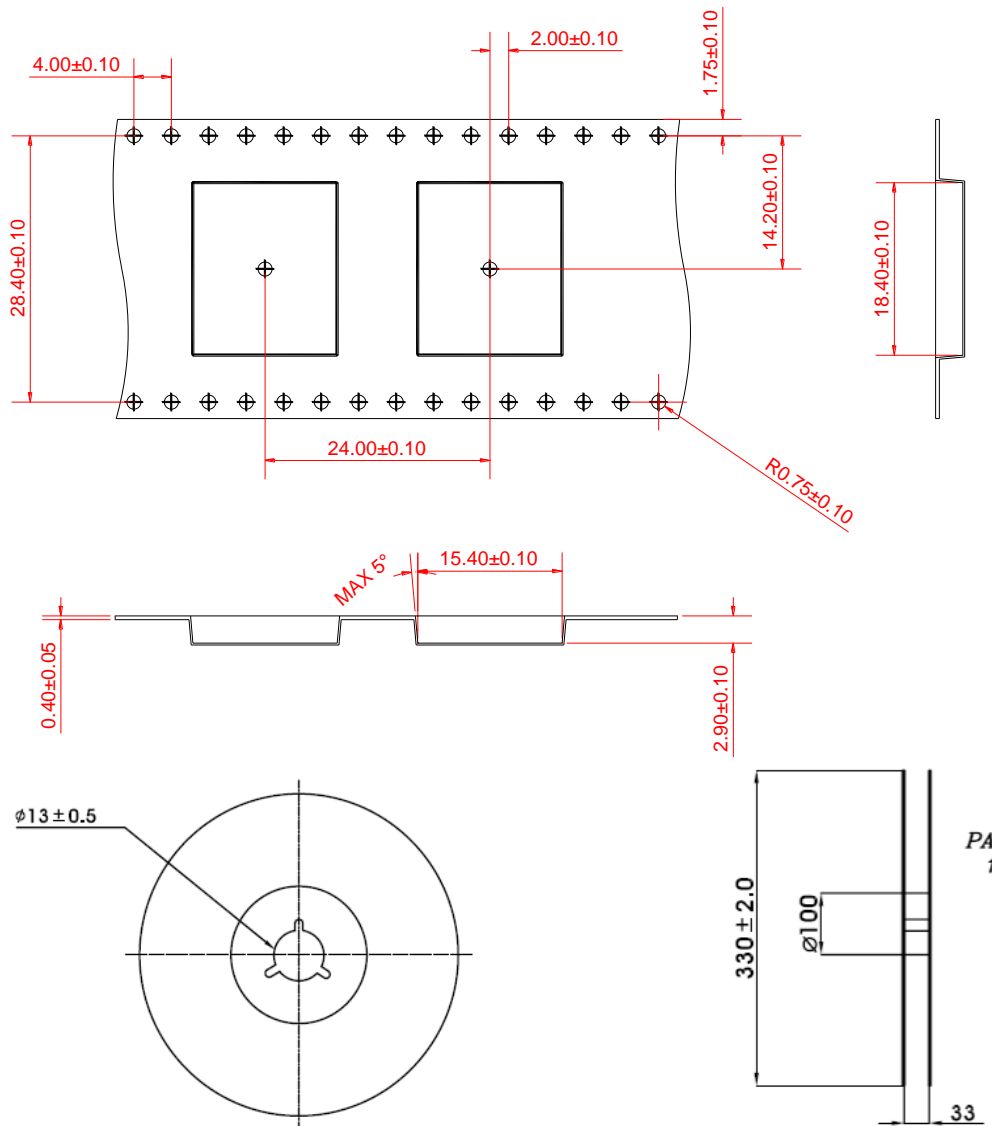


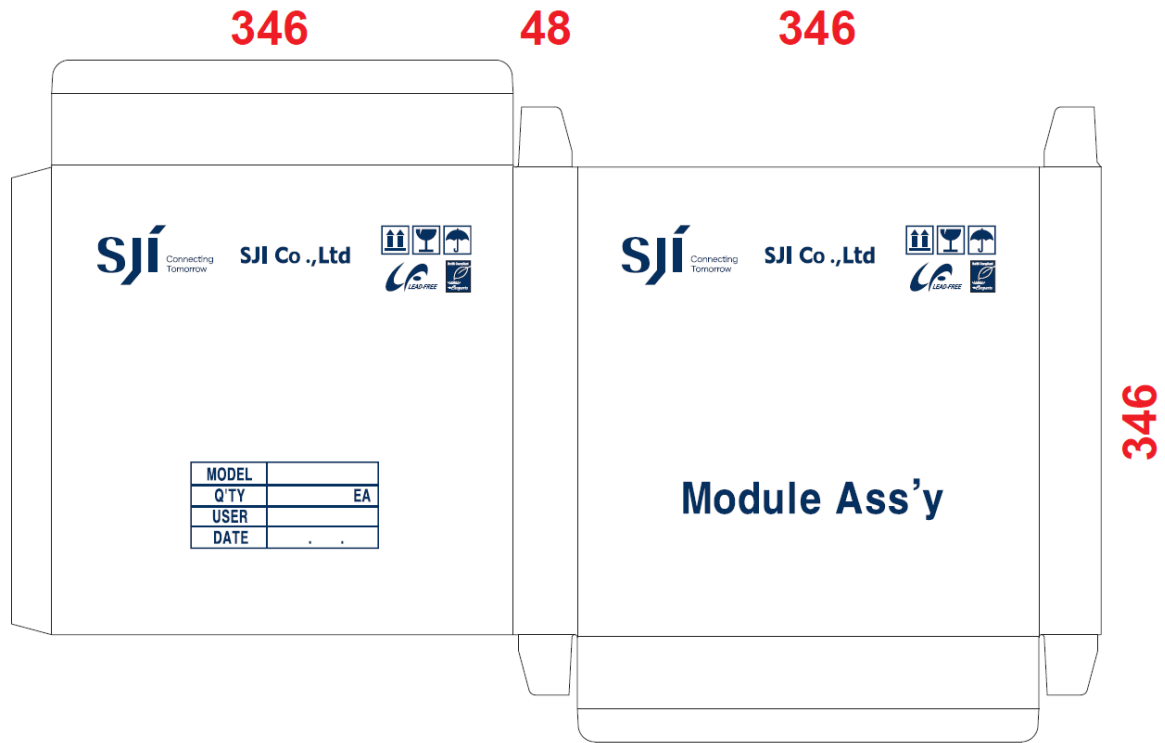
Figure 7-1: Reel packing

* Reel Bobbin size: 15.4 x 18.4 X 2.9mm(480pcs/Reel)

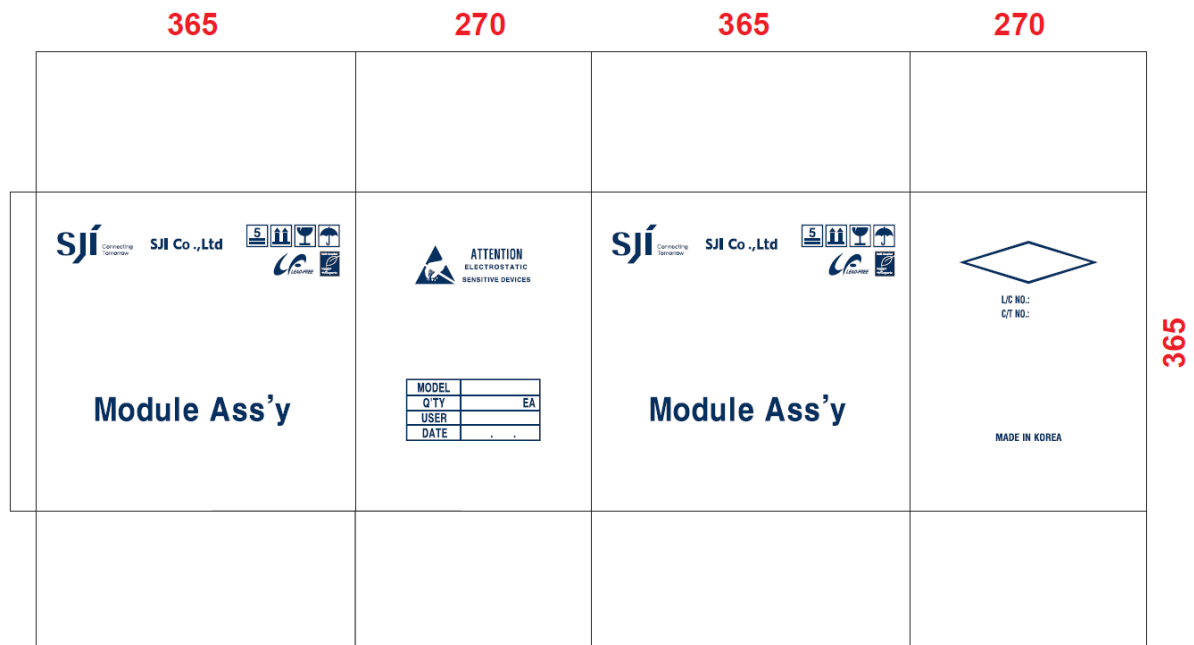
* Packing Q'ty: 2,400pcs/Box

7.2 Packing Box

- Inner Box : 346 X 18 X 346 mm



- Out Box : 365 X 270 X 365 mm



7.2 Packing Bag & Silica Gel

 A photograph of a white aluminum bag with a printed label. The label includes a 'CAUTION' section with a 'LEVEL 3' warning, a green recycling symbol, and Korean text. There are also smaller green symbols on the right side of the label.	 A photograph of a white silica gel desiccant packet. The packet is printed with 'DESI PAK' and 'DO NOT EAT' in large letters. It also includes the company name 'I-TWO TRADING CO., LTD.' and 'SEOUL, KOREA' along with other smaller text and logos.
<p>Aluminum Bag</p>	<p>Silica Gel(20g)</p>

8. Notice

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications.

SJIT MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE.

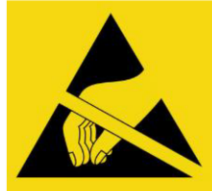
SJIT disclaims all liability arising from this information and its use. Use of SJIT devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless SJIT from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any SJIT intellectual property rights unless otherwise stated.

책임의 한계: 장치 및 응용 프로그램등과 관련하여 본 문서 및 관련 문서에 포함된 정보는 사용자의 편의를 위해서만 제공되며 업데이트로 대체 될 수 있습니다. 본 문서 및 관련 문서에 포함된 정보가 사용자의 제품 규격에 부합하는지 확인하는 것은 귀하의 책임입니다.

㈜에스제이아이티 또는 그 딜러는 손해 가능성에 대한 사전 인지 여부와 관계없이 본 계약에 따라 제공되는 정보와 장비, 부품 또는 서비스의 사용으로 발생할 수 있는 직접, 간접, 부수, 특별 또는 결과적 손해나 기대 이익의 손실 등 어떠한 다른 손해에 대하여 책임을 지지 않습니다.

장치 및 응용프로그램을 생명 유지 및 안전 용도로 사용하는 것은 전적으로 구매자의 위험 부담이며 구매자는 그러한 행위로 인하여 발생하는 일체의 손해, 청구, 소송 또는 경비로부터 ㈜에스제이아이티를 보호하고 면책하며, 면제 할 것에 동의합니다. 수정된 정보 및 Firmware는 ㈜에스제이아이티 기술지원 사이트에 게시를 하며, 개별적으로 통보하지 않습니다.

ESD Warning



This modules are ESD sensitive devices, appropriate precautions should be taken during the module assembly in the final product.

Mechanical impact and harsh tools must be avoided during the module assembly in the final product.

Product ESD specification :

- ▲ HBM $\pm 2\text{kV}$

The following precautions must be taken :

- ▲ Do not open the protective conductive packaging until you have use the following, and are at an approved anti-static work station.
- ▲ Use a conductive wrist strap attached to a good earth ground.
- ▲ If working on a prototyping board, use a soldering iron or station that is marked as ESD-safe.
- ▲ Use an approved anti-static mat to cover your work surface.